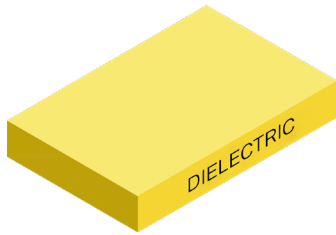


# BOND SHEET cured 2,2W (70µm–100µm)

## STANDARD CONSTRUCTION

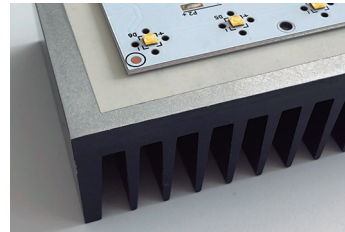


**Insulation thickness µm (mils)**  
70(2,8) / 100(3,9)

\*Other constructions available upon request

## DESCRIPTION

Dielectric polymerized glass reinforced in a bond sheet with high thermal conductivity. It is based on epoxy ceramic chemistry, and intended for improving thermal contact between two surfaces. Its high dielectric resistance added to its high thermal conductivity assures heat dissipation in critical power circuitry assuring high dielectric strength. Ideal for thermal insulating material, adhesive less, easy to assemble on PCBA and excellent dielectric performance.



UL Approved QMST2  
File: E47820  
IPC-4101



RoHS 3 / REACH  
Last updated compliance directive



Properties	BSC 70	BSC 100	UNITS	TOLERANCE	TEST METHOD
Thermal conductivity	2,2 (0,056)*	2,2 (0,056)*	W/mK (W/inK)	+/- 15%	ASTM D5470
Thermal Resistance	0,041	0,058	K/W	+/- 15%	ASTM D5470
Thermal impedance @10/30/50 psi	0,350 (0,054)*	0,5 (0,078)*	Kcm <sup>2</sup> / W (Kin <sup>2</sup> / W)	+/- 15%	ASTM D5470
Nominal thickness (pressed)	70 (2,8)	100 (2,9)	µm (mils)	+/- 15µm (0,6mils)	-
Filler type	Ceramic	Ceramic	-	-	-
Dielectric breakdown voltage, AC	≥4	≥6	kV	-	IPC TM 650 2.5.6.3
Continuous Working Temperature	130*	130	°C	-	UL-MOT
Volume Resistivity (los tenemos H Tg)	1.82E+14*	1.82E+14	Ohm-cm	-	ASTM D257
Surface Resistivity (los tenemos H Tg)	2.14E+13*	2.14E+13	Ohm	-	ASTM D257
Decomposition Temperature (Td) Initial	205*	205	°C	-	IPC-TM 650-2.3.41
Decomposition Temperature (Td) 5% loss	327*	327	°C	-	IPC-TM 650-2.3.41
Glass transition temperature of dielectric layer (by DSC)	120*	120	°C	-	IPC-TM 650-2.4.24
Permittivity	6,7 (0,170)*	6,7 (0,170)	pF/m (pF/in)	-	-
Flammability / Flame Rating	V-0**	V-0	class	-	UL-94
Density	1,6	1,6	gr/cm <sup>3</sup>	+/- 5%	

DELIVERY FORM
In cut to size sheets upon request

(\*) Thermal Conductivity and Impedance values may have a +/- 15% deviation.